

## REMARKS

Original claims 1-60 have been canceled. New claims 61-85 have been added. A reading of new claims 61-85 on the specification and drawings is as follows.

61. (new) A contact (**14B-Figure 5B**) for making an electrical connection with a component contact (**16-Figure 3A**) on a semiconductor component (**18-Figure 3B**) comprising:

a substrate (**12-Figure 5B**);

a plurality of spring segment leads (**22B-Figure 5B**) having a height on the substrate (**page 15, lines 21-24**);

a support member (**21B-Figure 5B**) attached to the leads, suspended on the substrate with the height (**page 15, lines 7-9**) and configured to support the component contact; and

a projection (**37-Figure 4B**) on the support member configured to penetrate the component contact.

62. (new) The contact of claim 61 wherein the leads are configured to twist the projection (**page 15, lines 13-18**).

63. (new) The contact of claim 61 wherein the leads have an extensible configuration (**page 14, line 11**).

64. (new) The contact of claim 61 wherein the plurality of spring segment leads have a spiral configuration (**page 15, line 13**).

65. (new) The contact of claim 61 wherein the support member comprises a plate (**page 5, line 3**).

66. (new) The contact of claim 61 wherein the projection comprises a blade (**page 14, line 7**).

67. (new) The contact of claim 61 wherein the component contact comprises a bumped contact (**page 4, line 7-8**).

68. (new) The contact of claim 61 further comprising a polymer material (**47-Figure 8E**) between the support member and the substrate.

69. (new) A contact (**14B-Figure 5B**) for making an electrical connection with a component contact (**16-Figure 3A**) on a semiconductor component (**18-Figure 3B**) comprising:

a substrate (**12-Figure 5B**);

a plurality of spring segment leads (**22B-Figure 5B**) having a height on the substrate (**page 15, lines 21-24**);

a support member (**21B-Figure 5B**) attached to the leads, suspended on the substrate with the height (**page 15, lines 7-9**) and configured to support the component contact and to travel by a distance equal to the height (**page 15, lines 21-24**);

a plurality of conductive vias (**32B-Figure 5B**) in the substrate, each spring segment lead in electrical communication with a conductive via; and

a projection (**37-Figure 4B**) on the support member configured to penetrate the component contact (**page 14, line 10**).

70. (new) The contact of claim 69 wherein the support member comprises a plate (**page 5, line 3**).

71. (new) The contact of claim 69 further comprising a terminal contact (**36B-Figure 5B**) on the substrate in electrical communication with the conductive vias.

72. (new) The contact of claim 69 wherein the spring segment leads are configured to exert a torque on the support member (**page 15, line 15**).

73. (new) The contact of claim 69 further comprising a polymer bump (**47-Figure 8F**) between the support member and the substrate.

74. (new) The contact of claim 69 wherein the height is from about 10-25 mils (**page 23, lines 26-27**).

75. (new) The contact of claim 69 wherein the component contact comprises a bumped contact (**page 4, line 7-8**).

76. (new) The contact of claim 69 wherein the substrate comprises a semiconductor material (**page 9, line 17**).

77. (new) A contact (**14C-Figure 4A**) for making an electrical connection with a component contact (**16-Figure 4B**) on a semiconductor component (**18-Figure 3B**) comprising:

a substrate (**12-Figure 4A**) having a recess (**20C-Figure 4A**);

a plurality of cantilevered leads (**22C-Figure 4A**) on the recess;

a support member (**21C-Figure 4A**) attached to the leads for movement into the recess, the support member configured

to support and electrically engage the component contact during the movement into the recess (**page 13, lines 29-32**); and

a projection (**37-Figure 4B**) on the support member.

78. (new) The contact of claim 77 wherein the recess has a depth and the movement into the recess is by an amount approximately equal to the depth (**page 14, lines 1-2**).

79. (new) The contact of claim 77 wherein the leads are configured to exert a torque on the support member (**page 15, line 15**).

80. (new) The contact of claim 77 wherein the projection comprises a blade configured to penetrate the component contact (**page 14, line 7**).

81. (new) The contact of claim 77 wherein the component contact comprises a bumped contact (**page 4, line 7-8**).

82. (new) The contact of claim 77 further comprising a plurality of conductive vias (**32B-Figure 5B**) in the substrate in electrical communication with the cantilevered leads.

83. (new) The contact of claim 77 wherein the leads have an extensible configuration (**page 14, line 11**).

84. (new) The contact of claim 77 wherein the substrate comprises a semiconductor material (**page 9, line 17**).

85. (new) The contact of claim 77 wherein the support member comprises a plate (**page 5, line 3**).

Conclusion

Favorable consideration and allowance of claims 61-85 is respectfully requested. An Information Disclosure Statement is being filed concurrently with this Preliminary Amendment. Should any issues arise that will advance this case to allowance, the Examiner is asked to contact the undersigned by telephone.

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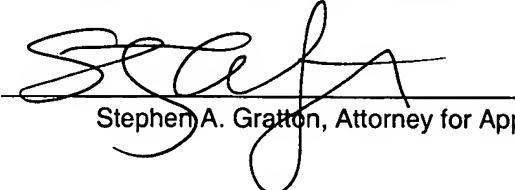
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